

Abstract:

The object of the present invention is to provide an adhesive composition capable of uniformly mixing the filler in the adhesive layer, capable of stably carrying out wire bonding before the simultaneous curing even when the process of carrying out simultaneous curing of the adhesive layer is applied when producing the multistacked package, and exhibiting an excellent adhesive strength after the curing; further particularly capable of accomplishing high package property in the semiconductor device; and to provide an adhesive sheet, having the adhesive layer comprising the adhesive composition, and a production method of a semiconductor device. An adhesive composition according to the present invention comprises an acrylic polymer (A), a heat curable resin (B) having a reactive double bond group, and a filler (C) having a reactive double bond group on a surface thereof, wherein the acrylic polymer (A) has a weight average molecular weight of 500,000 or more, and the heat curable resin (B) comprising an epoxy resin and a heat curing agent, in which at least one of the epoxy resin and the heat curing agent has the reactive double bond group.